**Bump Change from High Lead at Amkor Taiwan to Cu Pillar at Chip Bond and Qual of SOT23 Flip Chip on Lead using Cu Pillar at Carsem**

# Qualification Results Summary for SOT at CARSEM

| TEST | SPECIFICATION | SAMPLE SIZE | RESULT |
|---|---|---|---|
| Temperature Cycle (TC)* | JEDEC *JESD22-A104* | 3 x 77 | PASS |
| Solder Heat Resistance (SHR)* | JEDEC/IPC *J-STD-020* | 3 x 11 | PASS |
| Temperature, Humidity and Bias Test (THB)* | JEDEC *JESD22-A101* | 3 x 77 | PASS |
| High Temperature Storage (HTS) | JEDEC *JESD22-A103* | 1 x 77 | PASS |
| Electrostatic Discharge *Field Induced Charge Device Model* | ANSI/ESDA/JEDEC *JS-002-2014* | 3/voltage | PASS +/1250V |

* Preconditioned per JEDEEC/IPC J-STD0020.